

ABSTRACT OF THE DISCLOSURE

A surface of copper is brought into contact with an aqueous solution for forming a bonding layer for bonding resin comprising: (a) at least one
5 type of acid selected from inorganic acid and organic acid; (b) tin salt or tin oxide; (c) salt or oxide of at least one type of metal selected from the group consisting of: silver, zinc, aluminum, titanium, bismuth, chromium, iron, cobalt, nickel, palladium, gold, and platinum; (d) a reaction accelerator; and
10 (e) a diffusive retaining solvent, so that an alloy layer of tin and the at least one type of metal selected in (c) is formed on the surface of the copper. Subsequently, a portion of the alloy layer of the tin and the at least one type of metal selected in (c) other than a portion of the alloy layer that is a layer in which the copper, the tin, and the at least one type of metal selected in (c) are diffused is removed, so that a bonding layer for bonding resin containing
15 an alloy of copper, tin, and the at least one type of metal selected in (c) is formed on a surface of copper. Thus, adhesion between copper and resin can be enhanced. The present invention provides the above-mentioned bonding layer forming solution, a method of producing a copper-to-resin bonding layer using the solution, and a layered product obtained thereby.

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